1

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L1: Entry 1 of 1

File: DWPI

Jan 6, 1998

DERWENT-ACC-NO: 1998-116280

DERWENT-WEEK: 199811

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TITLE: Photosensitive composition - containing polymer with aliphatic side chain, and used in the manufacture of a semiconductor device

PATENT-ASSIGNEE:

ASSIGNEE

CODE

TOSHIBA KK

TOKE

PRIORITY-DATA:

1996JP-0156962

June 18, 1996

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

JP 10003169 A

January 6, 1998

N/A

014 G03F007/039

APPLICATION-DATA:

PUB-NO

APPL-DESCRIPTOR

APPL-NO

APPL-NO

JP10003169A

June 18, 1996

1996JP-0156962

N/A

INT-CL (IPC): C08L 33/04; C08L 101/00; C09D 133/04; G03F 7/004; G03F 7/039; H01L 21/027

ABSTRACTED-PUB-NO: JP10003169A BASIC-ABSTRACT:

Photosensitive compsn. contains a polymer cpd. which has a side chain with alicyclic construction to which at least one kind of substd. gp. of OH gp. and NO2 gp. is introduced or a heterocyclic construction to which S with two O being bonded is introduced.

USE - The compsn. is used for resist material used for fine processing in manufacture of a semiconductor element.

ADVANTAGE - The photosensitive compsn. for alkali development can form a resist pattern which has improved resolution, sensitivity, and dry etching resistance and also which does not cause any problems such as generation of cracking and separation from a substrate. Thereby, the photosensitive compsn. is effective for fine processing in manufacture of a high integrated semiconductor device.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: PHOTOSENSITISER COMPOSITION CONTAIN POLYMER ALIPHATIC SIDE CHAIN MANUFACTURE SEMICONDUCTOR DEVICE

DERWENT-CLASS: A89 G06 L03 P84 U11

CPI-CODES: A08-M08; A12-E07C; A12-L02B2; G06-D06; G06-F03C; G06-F03D; L04-C05;



EPI-CODES: U11-A06A;

ENHANCED-POLYMER-INDEXING: Polymer Index [1.1] 018; P0000; L9999 L2391; L9999 L2108 L2095; M9999 M2108 M2095 Polymer Index [1.2] 018; ND01; Q9999 Q7476 Q7330; Q9999 Q8684 Q8673 Q8606; Q9999 Q8673\*R Q8606; B9999 B4580 B4568; B9999 B3769 B3758 B3747; B9999 B3849\*R B3838 B3747; K9585 K9483; K9687 K9676; K9676\*R; K9712 K9676; K9416

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1998-038463 Non-CPI Secondary Accession Numbers: N1998-093192



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1. Document ID: <u>JP 10003169 A</u>

L1: Entry 1 of 1

File: DWPI

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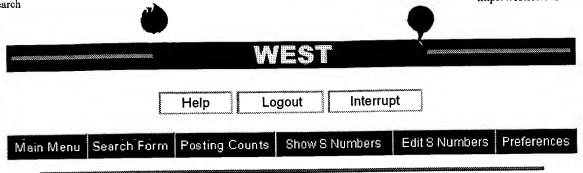
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Search History

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